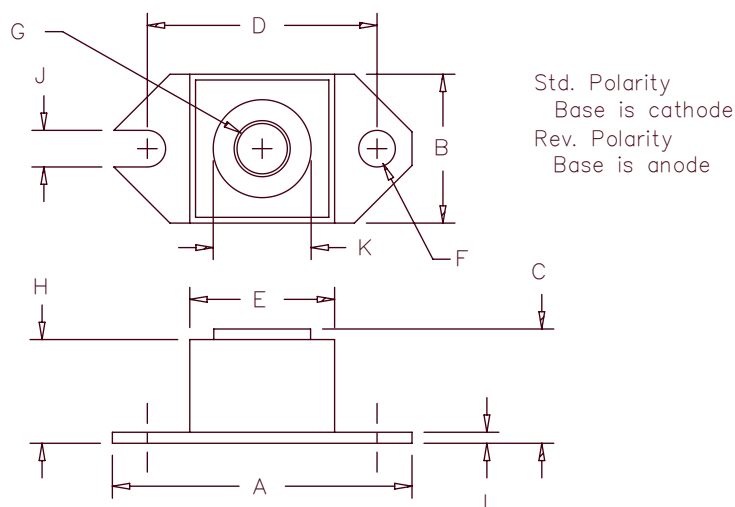


180 Amp Schottky Rectifier HS18135–HS18145



Dim.	Inches		Millimeter		Notes
	Minimum	Maximum	Minimum	Maximum	
A	1.52	1.56	38.61	39.62	
B	.725	.775	18.42	19.69	
C	.605	.625	15.37	15.88	
D	1.182	1.192	30.02	30.28	
E	.745	.755	18.92	19.18	Sq.
F	.152	.160	3.86	4.06	Dia.
G		1/4–20	UNC–2B		
H	.525	.580	13.34	14.73	
J	.156	.160	3.96	4.06	
K	.495	.505	12.57	12.83	Dia.
L	.120	.130	3.05	3.30	

HALF-PAK

Microsemi Catalog Number	Industry Part Number	Working Peak Reverse Voltage	Repetitive Peak Reverse Voltage	● Schottky Barrier Rectifier ● Guard Ring Protection ● Low Forward Voltage ● 175°C Junction Temperature ● V_{RRM} 35–45 Volts ● Reverse Energy Tested ● ROHS Compliant
HS18135*	181NQ035	35V	35V	
HS18140*	181NQ040	40V	40V	
HS18145*	181NQ045	45V	45V	
* Add Suffix R for Reverse Polarity				

Electrical Characteristics

Average forward current	$I_F(AV)$ 180 Amps	$T_C = 142^\circ\text{C}$, square wave, $R_{\theta JC} = 0.3^\circ\text{C/W}$
Maximum surge current	I_{FSM} 2500 Amps	8.3ms, half sine, $T_J = 175^\circ\text{C}$
Maximum repetitive reverse current	$I_R(OV)$ 2 Amps	$f = 1\text{ kHz}$, 1 μs square wave, $T_J = 25^\circ\text{C}$
Max peak forward voltage	V_{FM} 0.70 Volts	$I_{FM} = 180\text{A}$; $T_J = 25^\circ\text{C}$ *
Max peak reverse current	I_{RM} 150mA	V_{RRM} , $T_J = 125^\circ\text{C}$ *
Max peak reverse current	I_{RM} 4mA	V_{RRM} , $T_J = 25^\circ\text{C}$
Typical junction capacitance	C_J 7500pF	$V_R = 5.0\text{V}$, $T_J = 25^\circ\text{C}$, $f = 1\text{MHz}$

*Pulse test: Pulse width 300 μsec , Duty cycle 2%

Thermal and Mechanical Characteristics

Storage temp range	T_{STG}	-55°C to 175°C
Operating junction temp range	T_J	-55°C to 175°C
Max thermal resistance	$R_{\theta JC}$	0.3°C/W junction to case
Typical thermal resistance (greased)	$R_{\theta CS}$	0.12°C/W case to sink
Mounting Base Torque		15–25 inch pounds
Terminal Torque		20–40 inch pounds
Weight		1.1 ounces (32 grams) typical

HS18135–HS18145

Figure 1
Typical Forward Characteristics

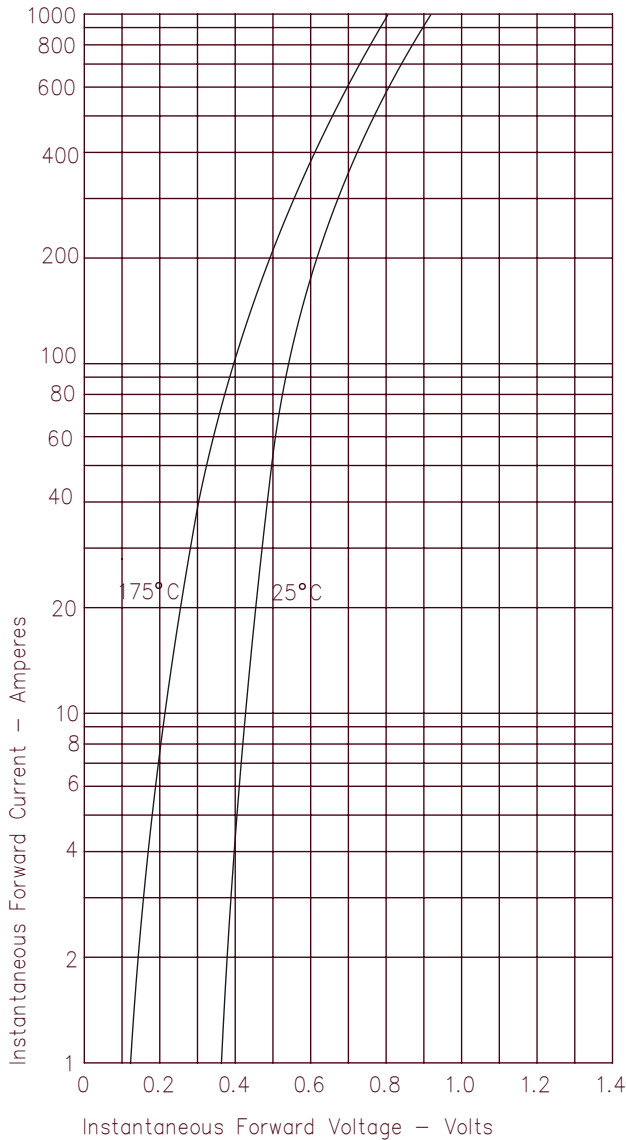


Figure 2
Typical Reverse Characteristics

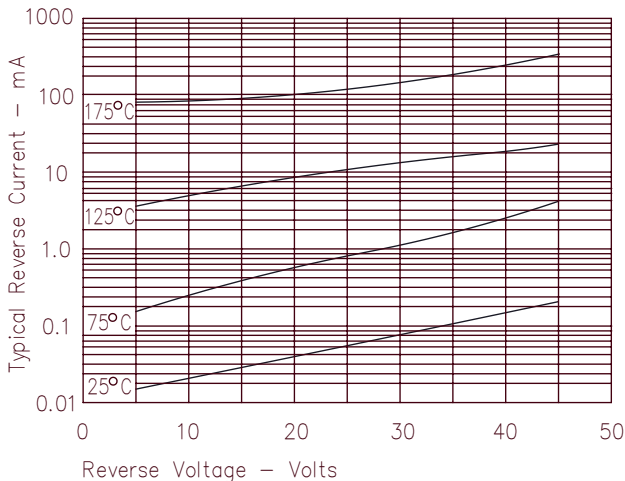


Figure 3
Typical Junction Capacitance

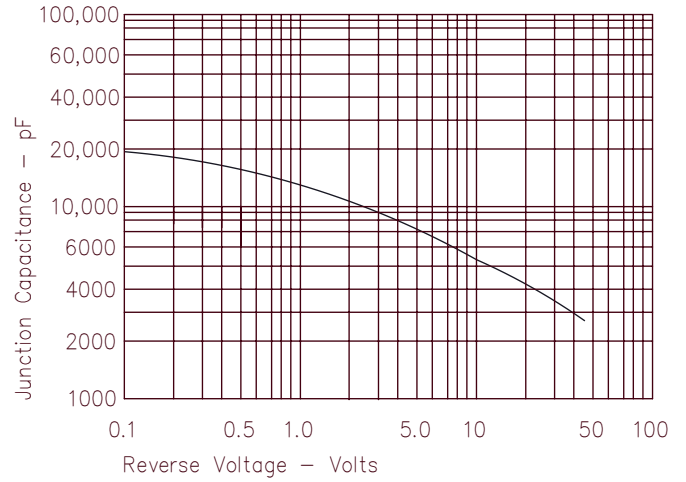


Figure 4
Forward Current Derating

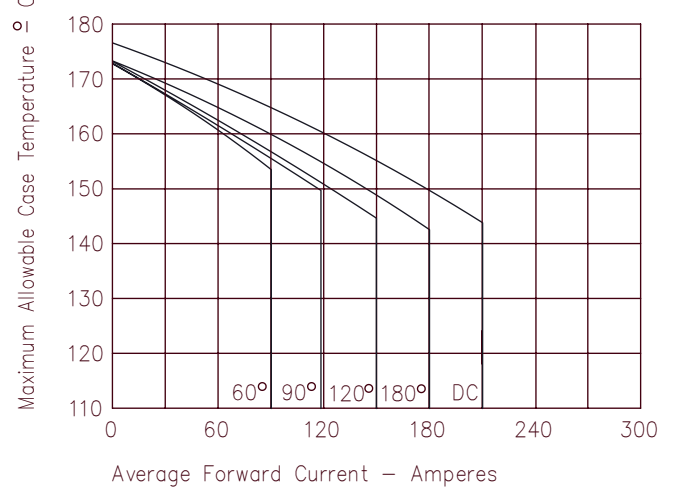
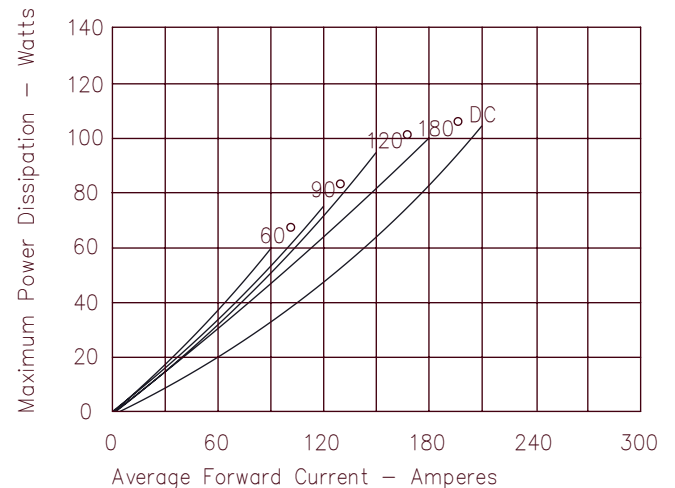


Figure 5
Maximum Forward Power Dissipation



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